

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN THE MATTER OF:

GROUP:

Huan-Ping SU

SERIAL NO.:

EXAMINER:

FILED: Concurrently Herewith

FOR: METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGES AND A  
CLAMPING DEVICE FOR MANUFACTURING A SEMICONDUCTOR PACKAGE

PRELIMINARY AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

MAIL STOP PATENT APPLICATIONS

S I R:

This Preliminary Amendment is being filed concurrently with the filing of  
the above-identified new patent application

All necessary fees in connection with this matter should be deducted from  
deposit account No. 01-1944.